

REMARKS

Reconsideration of the Advisory Action is respectfully requested in view of the following discussion.

The Examiner has asserted that wire bond pad connections (22) and solder ball array connections (23) on device (21) teach solder ball array connection and wire bond connections as claimed. This rejection is found in the Office Action dated April 1, 2003. The Examiner has also asserted in the advisory action that the prior art device "looks like" that claim citing MPEP § 2113. Applicant respectfully submits that the MPEP uses the language "the claimed product appears to be the same or similar to that of the prior art.

The MPEP places the burden on Applicant to come forward with evidence establishing an unobvious difference.

The difference between Applicant's claimed known good dye and JP 10-135281 is that contrary to the Examiner's statement, item 21 in the Japanese reference, is not a known good dye. Item 21 is a glass fiber and epoxy substrate (see attached copy of drawing with reference numerals labeled in accordance with the English translation of the specification). '281 shows only a single electrode pad (2) attached to the IC chip (1). Applicant claims an IC chip (known good dye) having two types of connections, namely solder ball array and wire bond connections. The IC chip of '281 has only a wire bond connection (electrode pad).

In '281, there is shown a wire (4) connecting the electrode pad up to the top of the glass fiber and epoxy substrate (21) to another electrode pad (22). Electrode pad (22) then connects to internal wiring (24) of the glass fiber epoxy substrate (21) which in turn connects to a pewter bump (23) located on top of the glass fiber and epoxy substrate (21) which has two different type of contacts, not the IC chip (known good dye) claimed by Applicant.

Still further, the electrode pad (2) is connected by a wire (3) to another pad (13) and to a test spin (12). Testing for '281 is provided on test pin (12), not by another test located on the IC chip (1).

Finally, claim 1 even further states that connections used for the known good dye test are not connected to the end use device when the known good dye is placed in the end use device. This is simply not true of the arrangement in '281 because test pin (12) remains active. The structure of '281 is, therefore, entirely different than that suggested by or taught by Applicant, as shown on the attached drawing with the appropriate labels placed thereon in accordance with the English translation of '281 of record in this case.

In view of the foregoing, it is respectfully submitted that the application is now in condition for allowance, and early action in accordance thereof is requested. In the event there is any reason why the application cannot be allowed in this current condition, it is respectfully requested that the Examiner contact

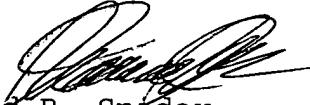
S/N: 09/832,884

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the undersigned at the number listed below to resolve any problems
by Interview or Examiner's Amendment.

Respectfully submitted,



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